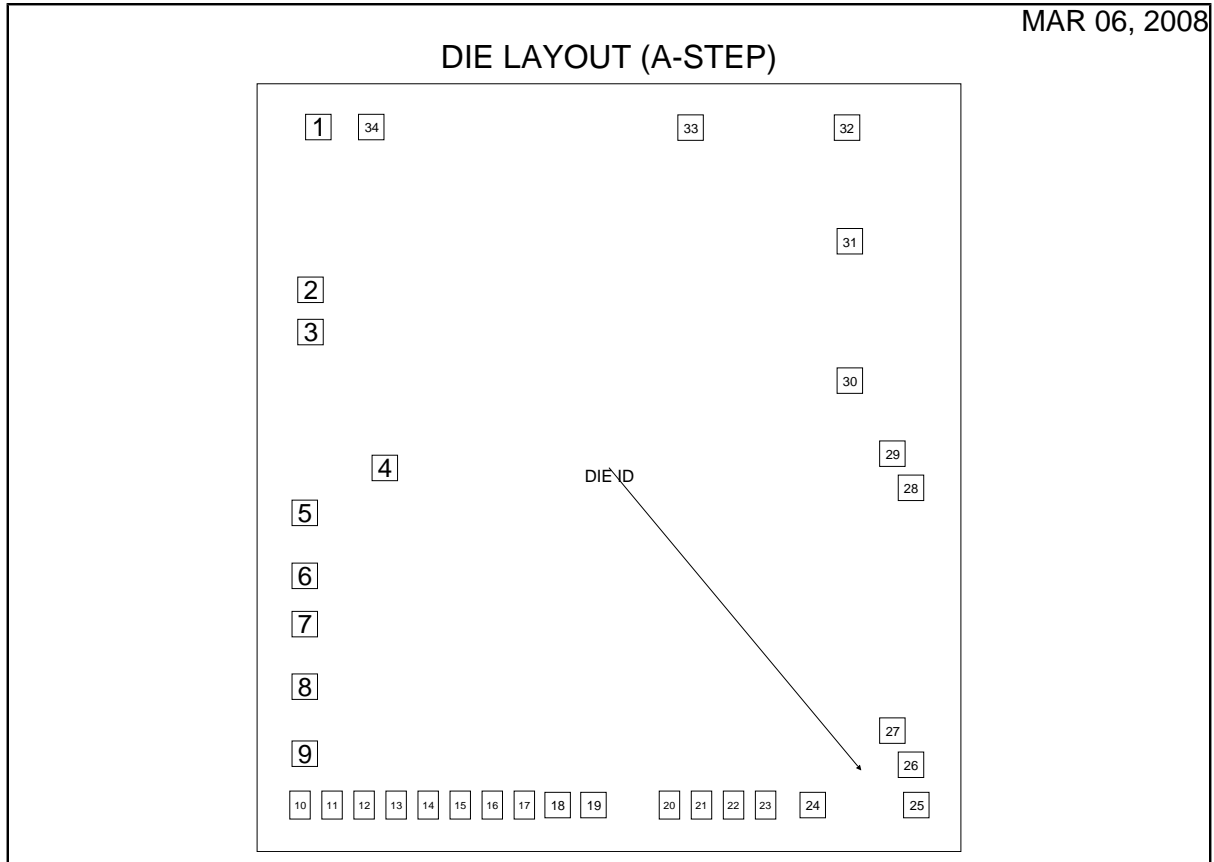


LM5575 MDC MWC  
SIMPLE SWITCHER® 75V, 1.5A STEP-DOWN SWITCHING REGULATOR



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM5575	Bond Pad Opening Size (min)	91.00µm x 91.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2514µm x 2743µm 99.0mils x 108.0mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	128.00µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
SD	1	-1038	1217	91	x	91
VIN	2	-1066	635	91	x	91
VIN	3	-1066	484	91	x	91
VIN	4	-801	-1	91	x	91
SYNC	5	-1087	-161	91	x	91
COMP	6	-1087	-386	91	x	91
FB	7	-1087	-559	91	x	91
RT	8	-1087	-782	91	x	91
RAMP	9	-1087	-1022	91	x	91
NC	10	-1104	-1205	73	x	100
NC	11	-989	-1205	73	x	100
NC	12	-875	-1205	73	x	100
NC	13	-760	-1205	73	x	100
NC	14	-646	-1205	73	x	100
NC	15	-531	-1205	73	x	100
NC	16	-417	-1205	73	x	100
NC	17	-302	-1205	73	x	100
AGND	18	-183	-1205	91	x	91
AGND	19	-55	-1205	91	x	91
NC	20	216	-1205	73	x	100
NC	21	330	-1205	73	x	100
NC	22	445	-1205	73	x	100
NC	23	559	-1205	73	x	100
SS	24	728	-1205	91	x	91
OUT	25	1098	-1205	91	x	91
PGND	26	1079	-1061	91	x	91
PGND	27	1012	-939	91	x	91
IS	28	1079	-72	91	x	91
IS	29	1012	50	91	x	91
SW	30	860	311	91	x	91
SW	31	860	809	91	x	91
PRE	32	850	1215	91	x	91
BST	33	291	1215	91	x	91
VCC	34	-849	1217	91	x	91

**LM5575 MDC MWC**  
**SIMPLE SWITCHER® 75V, 1.5A STEP-DOWN SWITCHING REGULATOR**

**Notes**

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